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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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Silicon PNP Epitaxial

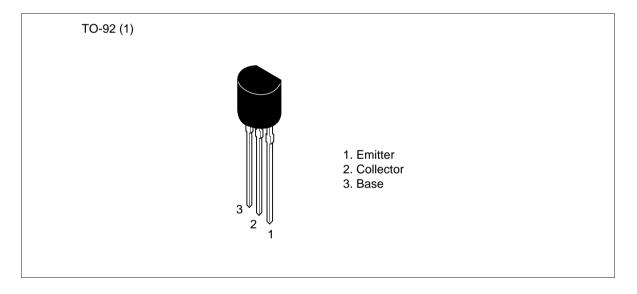


ADE-208-125 (Z) 1st. Edition Mar. 2001

Application

- Low frequency amplifier
- Complementary pair with 2SC1213 and 2SC1213A

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

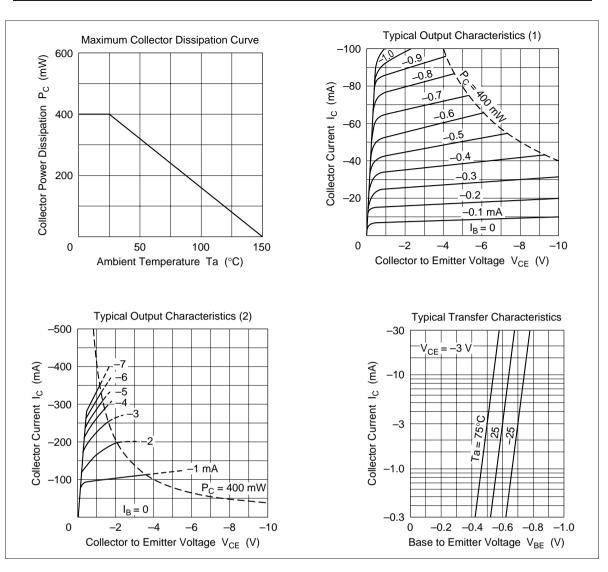
Item	Symbol	2SA673	2SA673A	Unit
Collector to base voltage	V _{CBO}	-35	-50	V
Collector to emitter voltage	V _{CEO}	-35	-50	V
Emitter to base voltage	V _{EBO}	-4	-4	V
Collector current	Ι _c	-500	-500	mA
Collector power dissipation	Pc	400	400	mW
Junction temperature	Tj	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

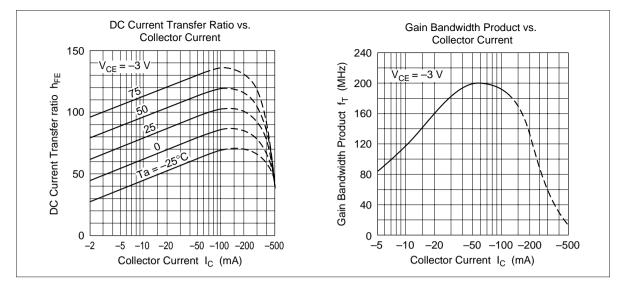
Electrical Characteristics (Ta = 25°C)

		2SA6	73		2SA673A				
Item	Symbol	Min	Тур	Max	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	-35	_	_	-50	_	_	V	$I_{c} = -10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	-35	_	_	-50	_	_	V	$I_{c} = -1 \text{ mA}, \text{ R}_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	-4	—	—	-4	_	_	V	$I_{\rm E} = -10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	—	—	-0.5	—		-0.5	μΑ	$V_{CB} = -20 \text{ V}, \text{ I}_{E} = 0$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	-0.2	-0.6	—	-0.2	-0.6	V	I _c = −150 mA, I _B = −15 mA* ²
DC current trnsfer ratio	h_{FE}^{*1}	60	_	320	60	_	320		$V_{ce} = -3 V,$ $I_c = -10 mA$
DC current trnsfer ratio	h _{FE}	10	—	—	10	—	_		$V_{ce} = -3 V,$ $I_c = -500 \text{ mA}^{*2}$
Base to emitter voltage	V_{BE}	—	-0.64		—	-0.64	_	V	$V_{ce} = -3 V,$ $I_{c} = -10 mA$
Notes: 1. The 2SA673 and 2SA673A are grouped by h _{FE} as follows. 2. Pulse test									

Ζ.	Z. Puise lest			
В	С	D		
60 to 120	100 to 200	160 to 320		

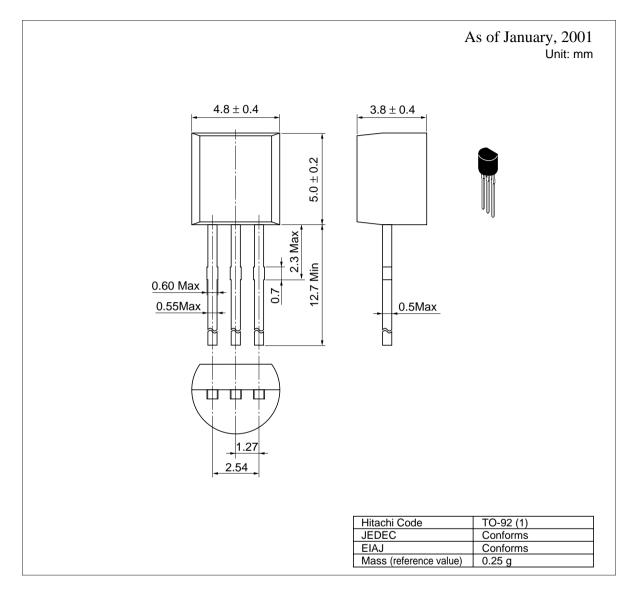
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Package Dimensions



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